

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Product Summary

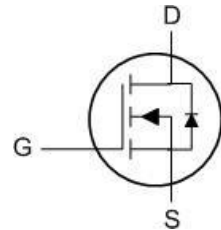
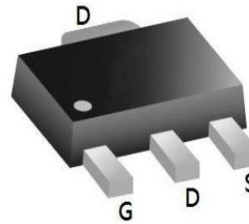


BVDSS	RDSON	ID
100V	110mΩ	6.5 A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

SOT89-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.5	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	3.2	A
I_{DM}	Pulsed Drain Current ²	12	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	125	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	80	$^\circ\text{C/W}$

Electrical Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	100	110	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics ^{note3}						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.95	3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance ^{note2}	V _{GS} = 10V, I _D = 3A	-	110	140	mΩ
Dynamic Characteristics ^{note4}						
C _{iss}	Input Capacitance	V _{DS} = 50V, V _{GS} = 0V, f = 1.0MHz	-	206	-	pF
C _{oss}	Output Capacitance		-	28.9	-	pF
C _{rss}	Reverse Transfer Capacitance		-	1.4	-	pF
Q _g	Total Gate Charge	V _{DS} = 50V, I _D = 3A, V _{GS} = 10V	-	4.3	-	nC
Q _{gs}	Gate-Source Charge		-	1.5	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	1.1	-	nC
Switching Characteristics ^{note4}						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 50V, I _{DS} =3A R _G = 2Ω, V _{GEN} = 10V	-	14.7	-	ns
t _r	Turn-On Rise Time		-	3.5	-	ns
t _{d(off)}	Turn-Off Delay Time		-	20.9	-	ns
t _f	Turn-Off Fall Time		-	2.7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current ^{note2}		-	-	6.5	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	A
V _{SD}	Drain to Source Diode Forward Voltage ^{note3}	V _{GS} = 0V, I _S =3A	-	-	1.3	V
t _{rr}	Body Diode Reverse Recovery Time	V _{GS} = 0V, I _F = 3A, di/dt =100A/μs	-	32.1	-	ns
Q _{rr}	Body Diode Reverse Recovery Time Charge		-	39.4	-	nC
I _{rrm}	Peak Reverse Recovery Current		-	2.1	-	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. $V_{DD}=50$ V, $R_G=50$ Ω , $L=0.3$ mH, starting $T_J=25$ $^{\circ}\text{C}$

Typical Characteristics

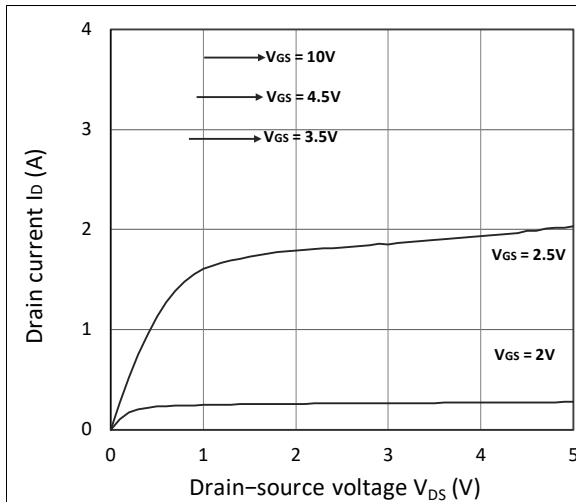


Figure 1. Output Characteristics

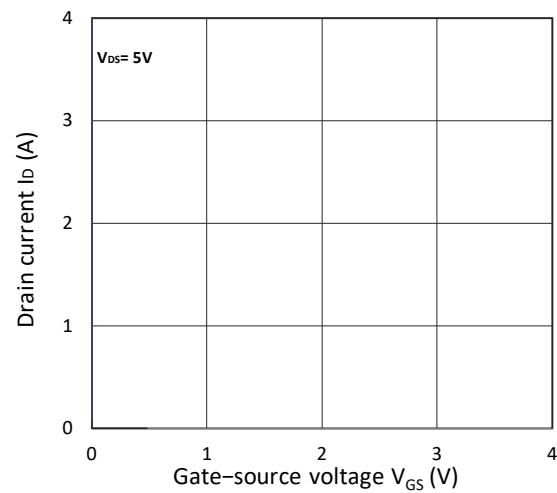


Figure 2. Transfer Characteristics

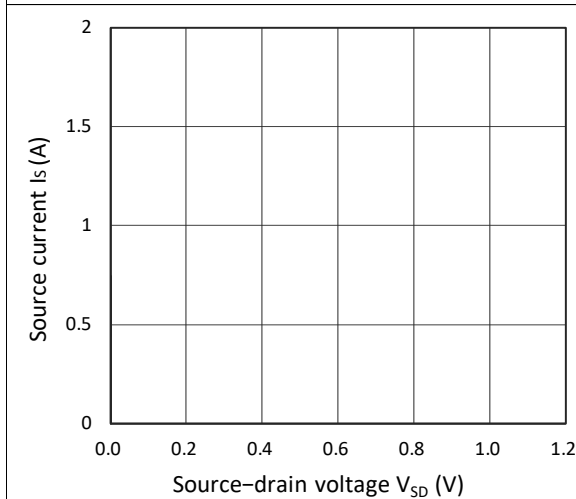


Figure 3. Forward Characteristics of Reverse

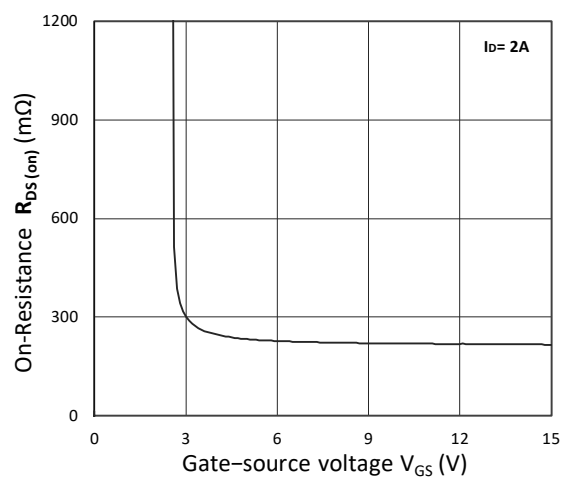


Figure 4. $R_{DS(on)}$ vs. V_{GS}

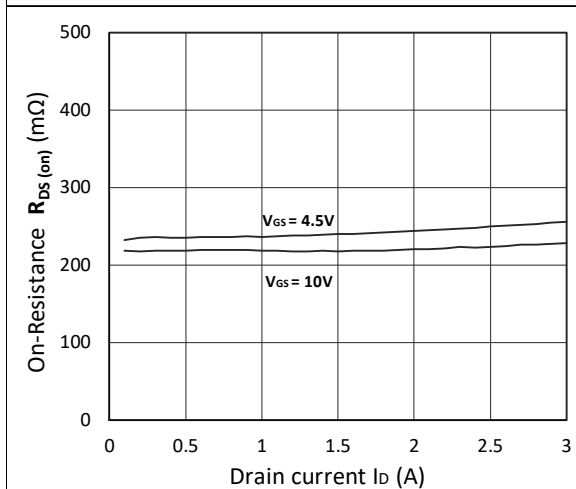


Figure 5. $R_{DS(on)}$ vs. I_D

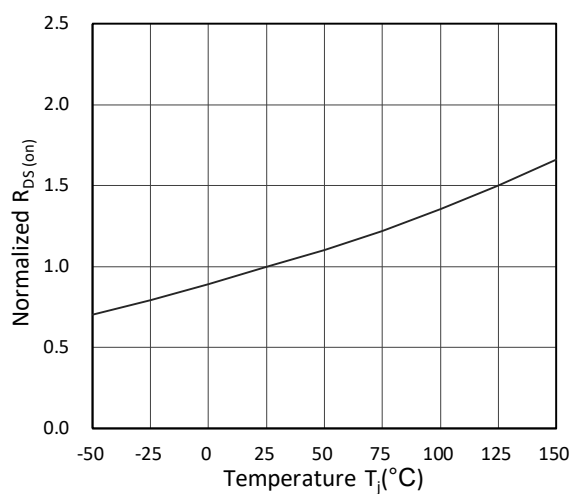


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

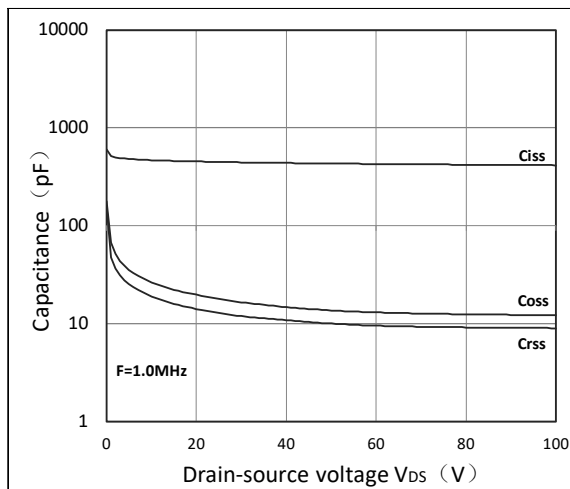


Figure 7. Capacitance Characteristics

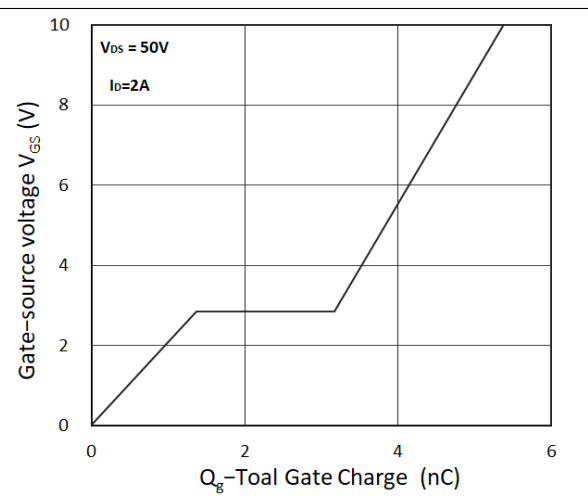
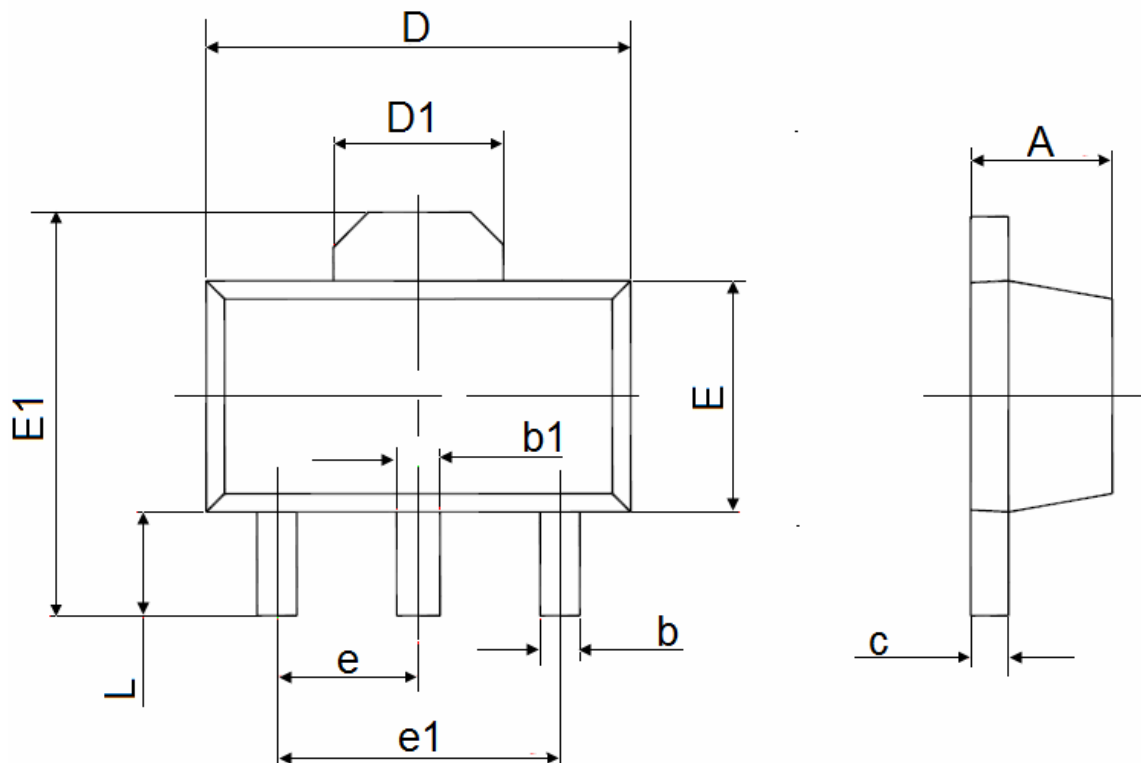


Figure 8. Gate Charge Characteristics

SOT-89-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047